

What is claimed is:

- 1 1. An electronic device, comprising:
2 a display unit; and
3 a host electrically connected to the display unit,
4 comprising a module structure having a first
5 substrate, at least one process unit, at least one
6 heat-dissipating device and at least one second
7 substrate, wherein the process unit is disposed on
8 the first substrate, and the second substrate is
9 disposed on the first substrate relative to the
10 process unit, and the second substrate and the
11 first substrate have the same structure and
12 texture.
- 1 2. The electronic device as claimed in claim 1, wherein
2 the first substrate and the second substrate are formed from
3 the same material.
- 1 3. The electronic device as claimed in claim 1, wherein
2 the first substrate and the second substrate are formed by
3 a multi-layer structure.
- 1 4. The electronic device as claimed in claim 1, wherein
2 the first substrate comprises a plurality of connecting
3 portions, and the heat-dissipating device is disposed on the
4 connecting portions.
- 1 5. The electronic device as claimed in claim 1, wherein
2 the process unit comprises CPU.

1 6. A module structure of an electronic device,
2 comprising:

3 a first substrate;

4 a process unit disposed on the first substrate;

5 a heat-dissipating device disposed on the first
6 substrate relative to the process unit; and

7 a second substrate disposed on the first substrate
8 relative to the process unit, having the same
9 structure and texture as the first substrate.

1 7. The module structure of the electronic device as
2 claimed in claim 6, wherein the first substrate and the second
3 substrate are formed from the same material.

1 8. The module structure of the electronic device as
2 claimed in claim 6, wherein the first substrate and the second
3 substrate are formed by a multi-layer structure.

1 9. The module structure of the electronic device as
2 claimed in claim 6, wherein the first substrate comprises a
3 plurality of connecting portions, and the heat-dissipating
4 device is disposed on the connecting portions.

1 10. The module structure of the electronic device as
2 claimed in claim 6, wherein the process unit comprises CPU.